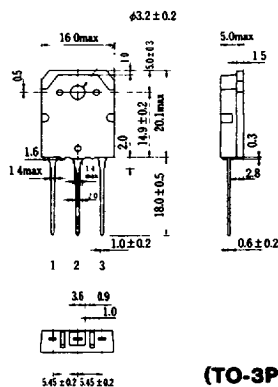
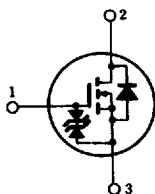


SILICON N-CHANNEL MOS FET

HIGH SPEED POWER SWITCHING

■ FEATURES

- Low On-Resistance
- High Speed Switching
- Low Drive Current
- No Secondary Breakdown
- Suitable for Switching Regulator and DC-DC Converter



1. Gate
2. Drain
(Flange)
3. Source
(Dimensions in mm)

■ **ABSOLUTE MAXIMUM RATINGS** ($T_a=25^{\circ}\text{C}$)

Item	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	900	V
Gate-Source Voltage	V_{GSS}	± 20	V
Drain Current	I_D	4	A
Drain Peak Current	$I_{D(pulse)}$ *	10	A
Body-Drain Diode Reverse Drain Current	I_{DR}	4	A
Channel Dissipation	P_{ch}^{**}	80	W
Channel Temperature	T_{ch}	150	°C
Storage Temperature	T_{sig}	-55~+150	°C

*PW $\leq 10\mu s$, duty cycle $\leq 1\%$

** Value at $T_c = 25^\circ\text{C}$

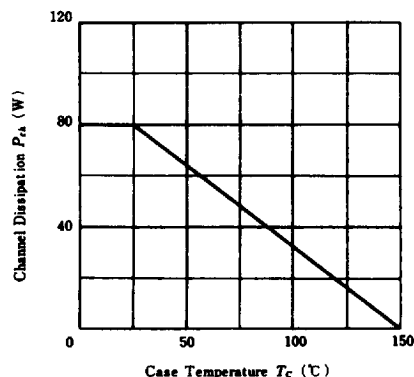
■ ELECTRICAL CHARACTERISTICS ($T_a=25^{\circ}\text{C}$)

Item	Symbol	Test Condition	min.	typ.	max.	Unit
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$I_D=10\text{mA}, V_{GS}=0$	900	—	—	V
Gate-Source Breakdown Voltage	$V_{(BR)GSS}$	$I_G=\pm 100\mu\text{A}, V_{DS}=0$	± 20	—	—	V
Gate-Source Leak Current	I_{GSS}	$V_{GS}=\pm 16\text{V}, V_{DS}=0$	—	—	± 10	μA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=720\text{V}, V_{GS}=0$	—	—	250	μA
Gate-Source Cutoff Voltage	$V_{GS(off)}$	$I_D=1\text{mA}, V_{DS}=10\text{V}$	2.0	—	4.0	V
Static Drain-Source on State Resistance	$R_{DS(on)}$	$I_D=2\text{A}, V_{GS}=10\text{V}^*$	—	4.0	5.5	Ω
Forward Transfer Admittance	$ y_{fs} $	$I_D=2\text{A}, V_{DS}=20\text{V}^*$	1.1	1.7	—	S
Input Capacitance	C_{iss}	$V_{DS}=10\text{V}, V_{GS}=0, f=1\text{MHz}$	—	650	—	pF
Output Capacitance	C_{oss}		—	350	—	pF
Reverse Transfer Capacitance	C_{rss}		—	250	—	pF
Turn-On Delay Time	$t_{d(on)}$	$I_D=2\text{A}, V_{GS}=10\text{V}, R_L=15\Omega$	—	15	—	ns
Rise Time	t_r		—	80	—	ns
Turn-Off Delay Time	$t_{d(off)}$		—	90	—	ns
Fall Time	t_f		—	70	—	ns
Body-Drain Diode Forward Voltage	V_{DF}	$I_F=4\text{A}, V_{GS}=0$	—	1.0	—	V
Body-Drain Diode Reverse Recovery Time	t_{rr}	$I_F=4\text{A}, V_{GS}=0, di_F/dt=100\text{A}/\mu\text{s}$	—	1200	—	ns

* Pulse Test

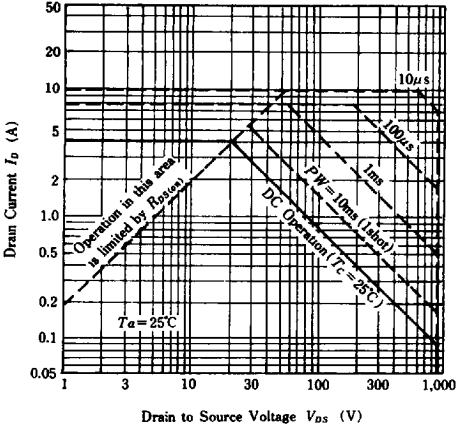
(TO-3P)

POWER VS. TEMPERATURE DERATING

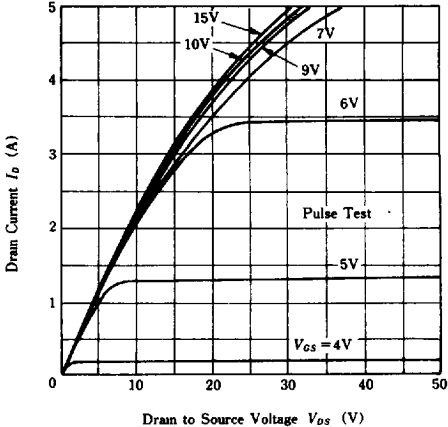


HITACHI/(OPTOELECTRONICS)

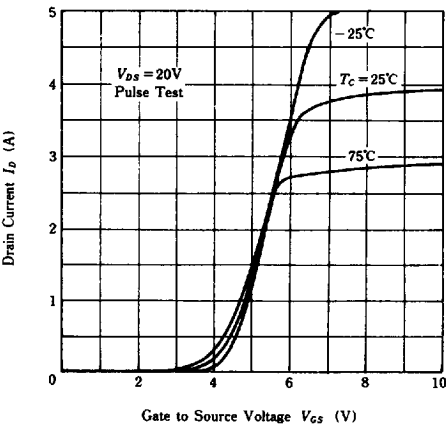
MAXIMUM SAFE OPERATION AREA



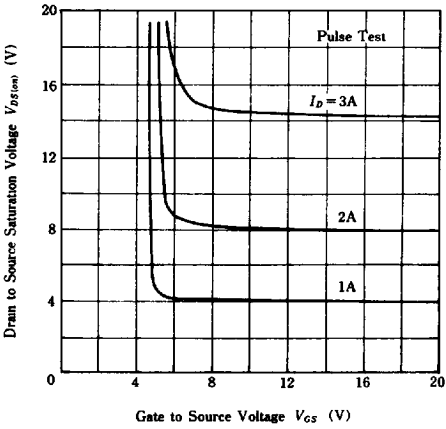
TYPICAL OUTPUT CHARACTERISTICS



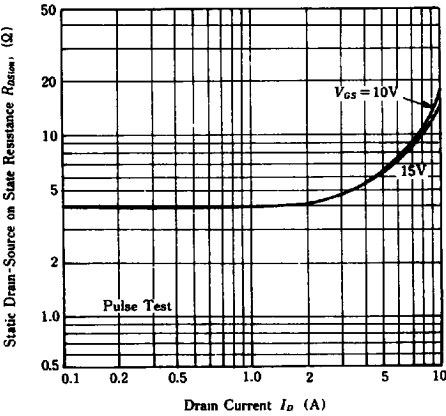
TYPICAL TRANSFER CHARACTERISTICS



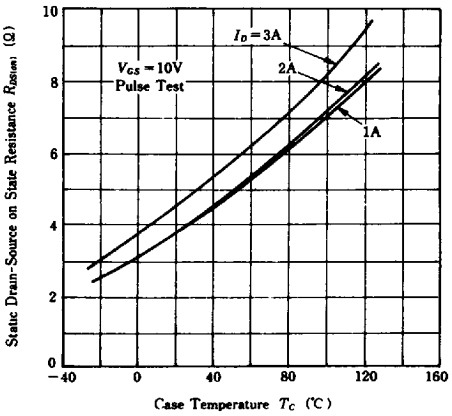
DRAIN-SOURCE SATURATION VOLTAGE VS. GATE-SOURCE VOLTAGE



STATIC DRAIN-SOURCE ON STATE RESISTANCE VS. DRAIN CURRENT

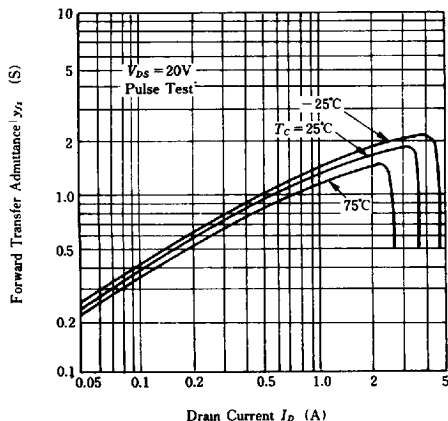


STATIC DRAIN-SOURCE ON STATE RESISTANCE VS. TEMPERATURE

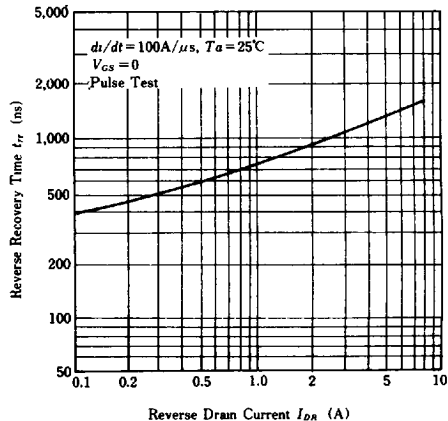


HITACHI/(OPTOELECTRONICS)

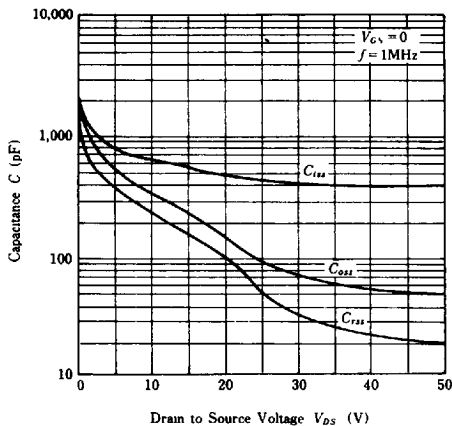
FORWARD TRANSFER ADMITTANCE
VS. DRAIN CURRENT



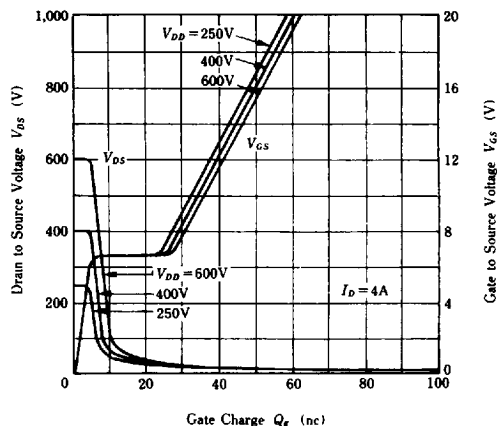
BODY-DRAIN DIODE REVERSE
RECOVERY TIME



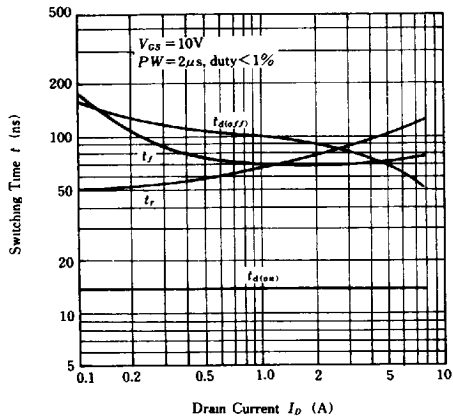
TYPICAL CAPACITANCE
VS. DRAIN-SOURCE VOLTAGE



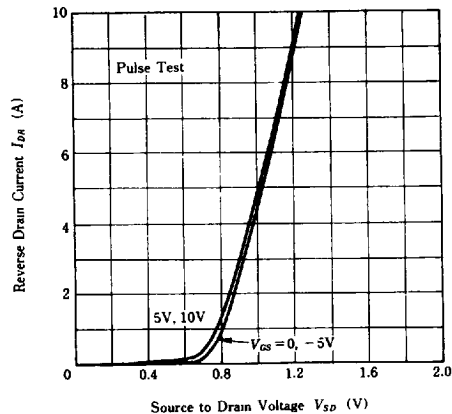
DYNAMIC INPUT CHARACTERISTICS



SWITCHING CHARACTERISTICS

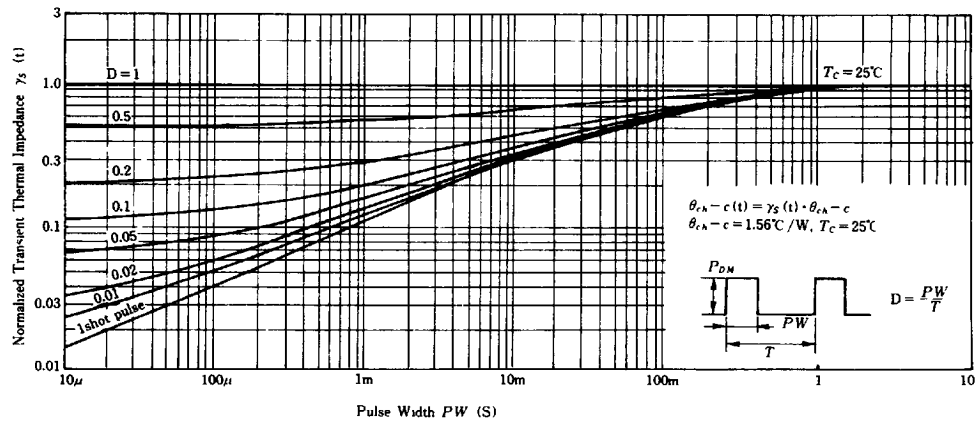


REVERSE DRAIN CURRENT VS.
SOURCE TO DRAIN VOLTAGE

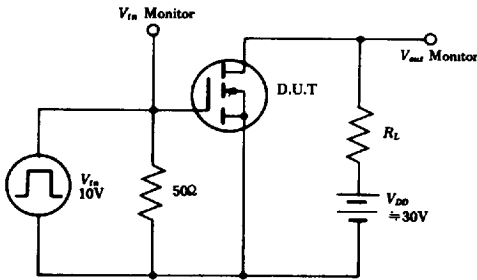


HITACHI/(OPTOELECTRONICS)

NORMALIZED TRANSIENT THERMAL IMPEDANCE VS. PULSE WIDTH



SWITCHING TIME TEST CIRCUIT



WAVEFORMS

